Allegro Sensor IC Package Portfolio

Allegro Sensor ICs

Allegro MicroSystems, Inc. is a leader in developing and manufacturing innovative, reliable, high-performance Hall-effect magnetic sensor ICs. The development of Allegro sensor ICs not only includes leading edge innovations in the area of integrated circuit design but also includes application specific innovation in the area of custom package design.

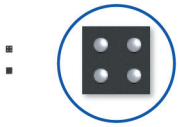
A small sampling of Allegro's custom packaging developments include:

- Proprietary, integrated magnet packages that simplify magnetic system design in automotive speed sensing applications. See the SE, SG, SH and SJ packages.
- Revolutionary, integrated current sensing packages with high bandwidth magnetic design features. See the SOIC, QSOP and CA/CB packages with integrated, low resistance current conductors and the 1 mm thick KT package.
- Small footprint, low profile DFN packages for communications and consumer products. See the EW and CG packages.

The package options shown below are a sampling of Allegro's most recent, high technology packages.
For specific package information, please visit Allegro's website at: **www.allegromicro.com/en/Products/Packaging**.

Low Profile, Smallest Footprint Packages

CG (WLCSP)
Terminals: 4
Size: .96 x .96 mm body width



EW (DFN)
Terminals: 6
Size: 1.5 x 2 mm body width

Surface Mount Packages

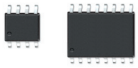
LH (SOT23W)
Terminals: 3

L/LC (SOIC-8)
Terminals: 8

Current Sensing Packages with Integrated Conductors

CA/CB
Terminals: 5

L/LC (SOIC-8 and SOIC-16)
Terminals: 8, 16



LF (QSOP-24)
Terminals: 24

Single In-Line Packages

UA (TO-92)
Terminals: 3

K
Terminals: 4

KE
Terminals: 4

KT
Terminals: 4

KN
Terminals: 4

Integrated Magnet Packages

SE
Terminals: 4

SG
Terminals: 4

SH
Terminals: 4

SJ
Terminals: 4

Please Note: Package sizes are photographed to show relative scale.

Allegro® MicroSystems, Inc.

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